



## Three Phase Bridge

Reverse Voltage - 1600 Volts  
Forward Current - 200 Amperes

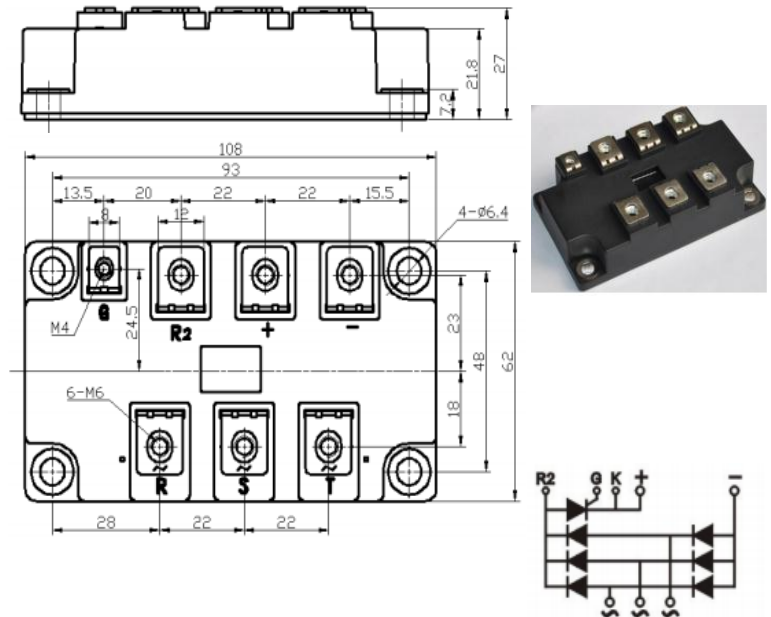
### Features

- Blocking voltage: 1600V
- Three Phase Bridge and a Thyristor
- Isolated Module package

### Applications

- Inverter for AC or DC motor control
- Current stabilized power supply
- Switching power supply

- Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.



Package Outline Dimensions in Millimeters

### Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

TYPE	VRRM	VRSM
MDST200-16	1600V	1700V

Characteristics	Symbol	Item	Values	Unit
Three phase, full wave Tc=100°C	ID	Output Current(D.C.)	200	A
t=10mS Tvj =45°C	IFSM	Surge forward current	2240	A
t=10mS Tvj =45°C	I <sup>2</sup> t	Circuit Fusing Consideration	25080	A <sup>2</sup> s
a.c.50HZ;r.m.s.;1min	Visol	Isolation Breakdown Voltage(R.M.S)	3000	V
	Tvj	Operating Junction Temperature	-40 to + 150	°C
	Tstg	Storage Temperature	-40 to + 125	
To terminals(M4) To terminals(M6)	Mt	Mounting Torque	2±15% 5±15%	Nm
To heatsink(M6)	Ms		5±15%	Nm
	Weight	Module (Approximately)	360	g
Junction to Case	Rth(j-c)	Thermal Impedance, max	0.12	°C/W
Case to Heatsink	Rth(c-s)	Thermal Impedance, max	0.10	°C/W
T=25°C IF=200A	VFM	Forward Voltage Drop, max	Min    Typ    Max	
			/       /       1.45	V
Tvj =25°C ,VRD=VRRM Tvj =150°C ,VRD=VRRM	IRD	Repetitive Peak Reverse Current, max	/       /       0.1 9	mA



Characteristics	Symbol	Item	Values			Unit
$T_c=90^{\circ}\text{C}$ , Single Phase half wave $180^{\circ}$ conduction	$I_{TAV}$	Average On-State Current	200			A
$T_{vj}=45^{\circ}\text{C}$ $t=10\text{ms}$ (50Hz),, sine $V_R=0$	$I_{TSM}$	Surge On-State Current	1900			A
	$I^2t$	Circuit Fusing Consideration	18050			$\text{A}^2\text{S}$
a.c.50HZ;r.m.s.;1min	Visol	Isolation Breakdown Voltage(R.M.S)	3000			V
	$T_{vj}$	Operating Junction Temperature	-40 to + 150			$^{\circ}\text{C}$
	$T_{stg}$	Storage Temperature	-40 to + 150			$^{\circ}\text{C}$
$T_{vj}=T_{vjM}$ , $V_D=1/2V_{DRM}$ , $I_G=100\text{mA}$ $d_iG/dt=0.1\text{A/us}$	$di/dt$	Critical Rate of Rise of On-State Current	150			$\text{A/us}$
$T_{vj}=T_{vjM}$ , $V_D=2/3V_{DRM}$ , linear voltage rise	$dv/dt$	Critical Rate of Rise of Off-State Voltage, min	500			$\text{V/us}$
Junction to Case	$R_{th(j-c)}$	Thermal Impedance, max	0.14			$^{\circ}\text{C/W}$
Case to Heatsink	$R_{th(c-s)}$	Thermal Impedance, max	0.10			$^{\circ}\text{C/W}$
$T=25^{\circ}\text{C}$ $I_T=200\text{A}$	$V_{TM}$	Peak On-State Voltage, max.	Min.	Typ	Max	
			/	/	1.65	V
$T_{vj}=T_{vjM}$ , $V_R=V_{RRM}$ , $V_D=V_{DRM}$	$I_{RRM}/I_{DRM}$	Repetitive Peak Reverse Current, max /Repetitive Peak Off-State Current,max	/	/	30	mA
$T_{vj}=T_{vjM}$	$V_{TO}$	Threshold voltage	/	/	0.9	V
	$R_t$	Slope resistance, max	/	/	2	$\text{m}\Omega$
$T_{vj}=25^{\circ}\text{C}$ , $V_D=6\text{V}$	$V_{GT}$	Gate Trigger Voltage, max	/	/	3	V
$T_{vj}=25^{\circ}\text{C}$ , $V_D=6\text{V}$	$I_{GT}$	Gate Trigger current, max	/	/	150	mA
$T_{vj}=125^{\circ}\text{C}$ , $V_D=2/3V_{DRM}$	$V_{GD}$	Required DC gate voltage , max	/	/	0.25	V
$T_{vj}=125^{\circ}\text{C}$ , $V_D=2/3V_{DRM}$	$I_{GD}$	Required DC gate current , max	/	/	6	mA
$T_{vj}=25^{\circ}\text{C}$ , $R_G=33\Omega$	$I_L$	Latching current, max	/	300	600	mA
$T_{vj}=25^{\circ}\text{C}$ , $V_D=6\text{V}$	$I_H$	Holding current, max	/	150	250	mA
$T_{vj}=25^{\circ}\text{C}$	$t_{gd}$	Gate controlled delay time	1			$\mu\text{s}$
$T_{vj}=T_{vjM}$	$t_q$	Circuit commutated turn-off time	100			$\mu\text{s}$

### Performance Curves

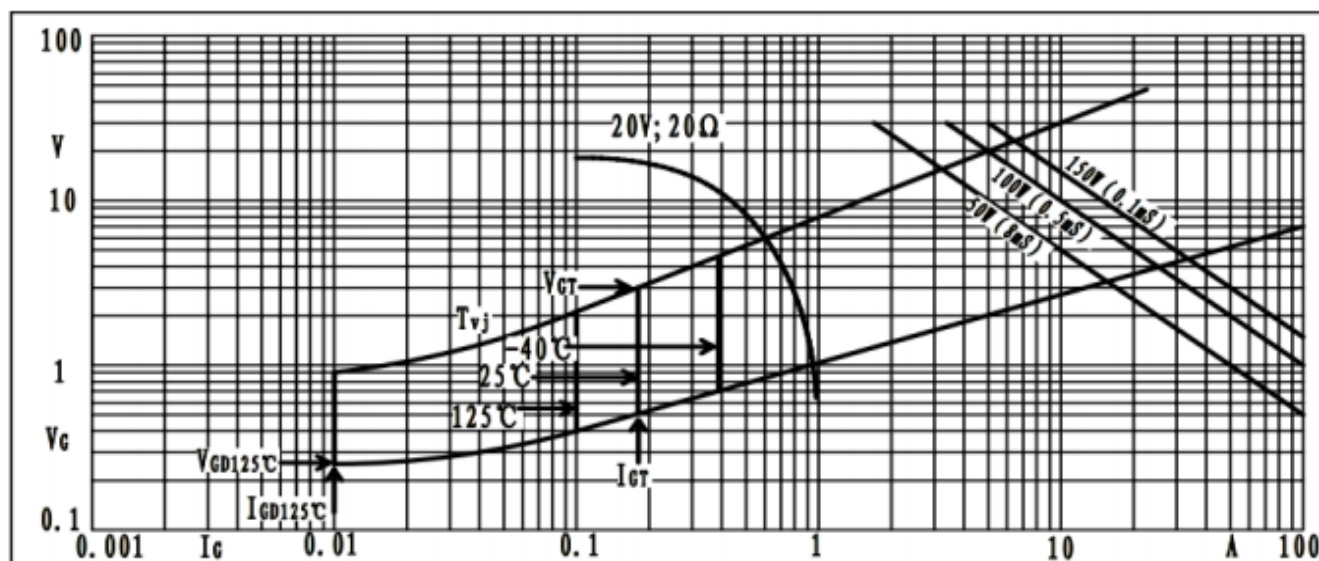


Fig1. Gate trigger characteristics

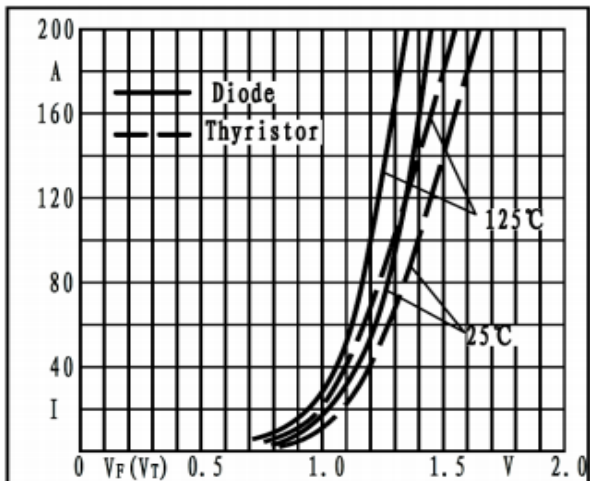


Fig2. Forward characteristics

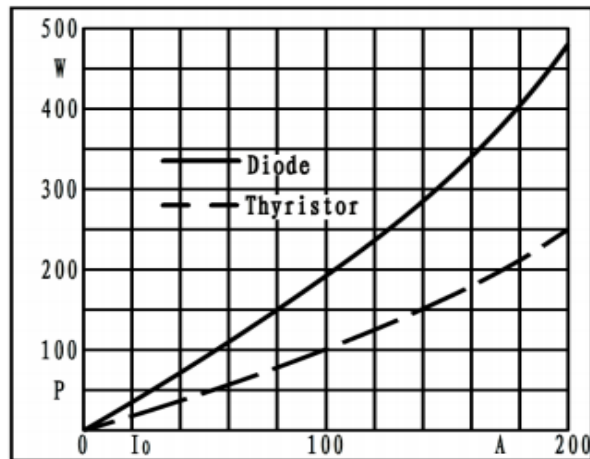


Fig3. Power dissipation

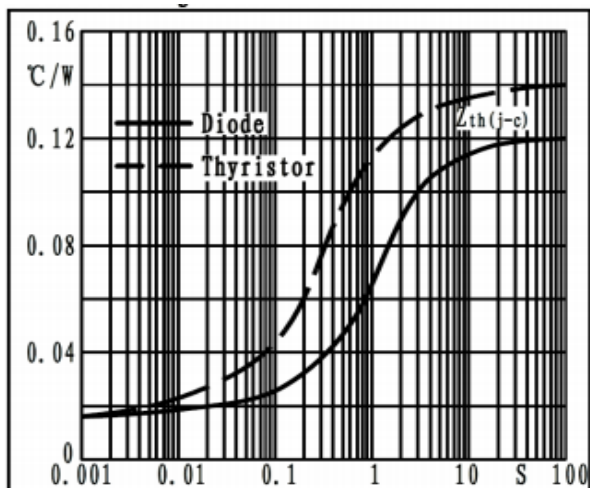


Fig4. Transient thermal impedance

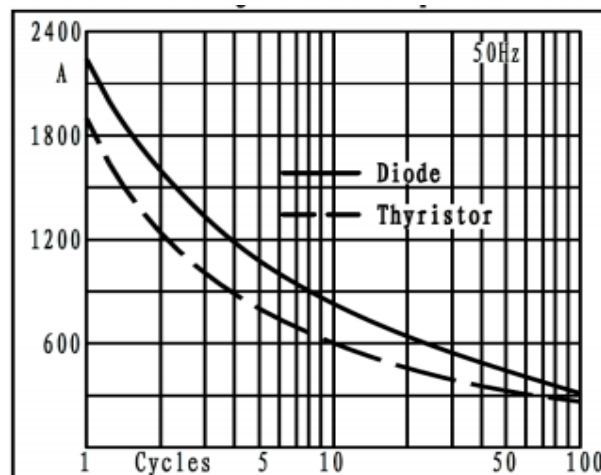


Fig5. Max non-repetitive forward surge current

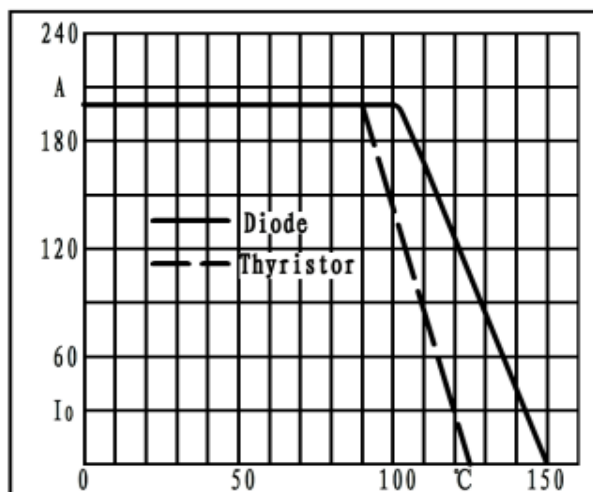


Fig6. Forward current derating curve

The curve above is for reference only.



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